

SN65C1168E-SEP Single-Event Latch-Up (SEL) Radiation Report



ABSTRACT

The purpose of this study was to characterize the effects of heavy-ion irradiation on the single-event latch-up (SEL) performance of the SN65C1168E-SEP, dual differential drivers and receivers. Heavy-ions with an LET_{EFF} of 43 MeV-cm²/mg were used to irradiate the devices with a fluence of 1×10^7 ions/cm². The results demonstrate that the SN65C1168E-SEP is SEL-free up to $LET_{EFF} = 43$ MeV-cm²/mg at 125°C.

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Trademarks

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1 Overview

The SN65C1168E-SEP consist of dual drivers and dual receivers powered from a single 5-V supply. This device meets the requirements of TIA/EIA-422-B and ITU recommendation V.11.

<https://www.ti.com/product/SN65C1168E-SEP>

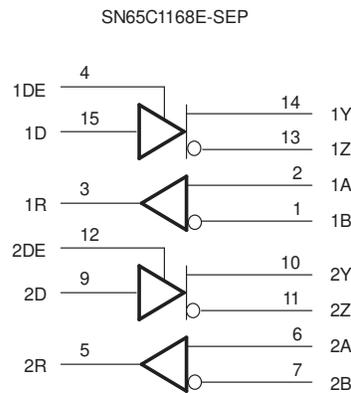
Table 1-1. Overview Information

DESCRIPTION	DEVICE INFORMATION
TI Part Number	SN65C1168E-SEP
MLS Number	SN65C1168EMPWTSEP
Device Function	Radiation Hardened RS-422 Dual Differential Drivers and Receivers in Space Enhanced Plastic
Technology	LBC3S
Exposure Facility	Radiation Effects Facility, Cyclotron Institute, Texas A&M University
Heavy Ion Fluence per Run	$1 \times 10^6 - 1 \times 10^7$ ions/cm ²
Irradiation Temperature	125°C (for SEL testing)

2 SEE Mechanisms

The primary single-event effect (SEE) events of interest in the SN65C1168E-SEP are single-event latch-up (SEL). From a risk/impact point-of-view, the occurrence of an SEL is potentially the most destructive SEE event and the biggest concern for space applications. The LBC3S was used for the SN65C1168E-SEP. CMOS circuitry introduces a potential for SEL susceptibility. SEL can occur if excess current injection caused by the passage of an energetic ion is high enough to trigger the formation of a parasitic cross-coupled PNP and NPN bipolar structure (formed between the p-sub and n-well and n+ and p+ contacts). The parasitic bipolar structure initiated by a single-event creates a high-conductance path (inducing a steady-state current that is typically orders-of-magnitude higher than the normal operating current) between power and ground that persists (is “latched”) until power is removed or until the device is destroyed by the high-current state. The process modifications applied for SEL-mitigation were sufficient as the SN65C1168E-SEP exhibited no SEL with heavy-ions up to an LET_{EFF} of 43 MeV-cm²/mg at a fluence of 10⁷ ions/cm² and a chip temperature of 125°C.

This study was performed to evaluate the SEL effects with a bias voltage of 5.5 V on V_S Supply Voltage. Heavy ions with LET_{EFF} = 43 MeV-cm²/mg were used to irradiate the devices. Flux of 10⁵ ions/s-cm² and fluence of 10⁷ ions/cm² were used during the exposure at 125°C temperature.



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Figure 2-1. Functional Block Diagram of the SN65C1168E-SEP

3 Test Device and Test Board Information

The SN65C1168E-SEP is packaged in a 16-pin, TSSOP shown with pinout in Figure 3-1. Figure 3-2 shows the SN65C1168E-SEP bias diagram.

SN65C1168E-SEP pinout diagram. The package was decap'ed to reveal the die face for all heavy ion testing.

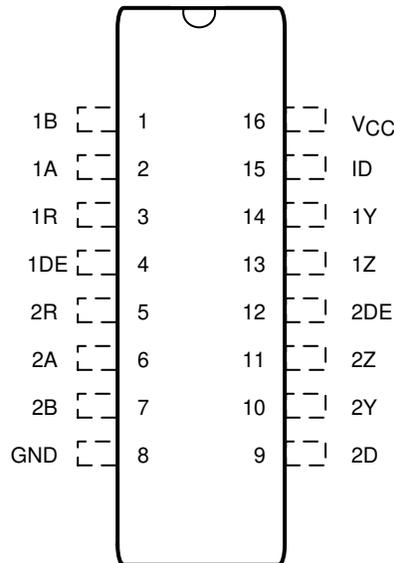


Figure 3-1. SN65C1168E-SEP Pinout Diagram

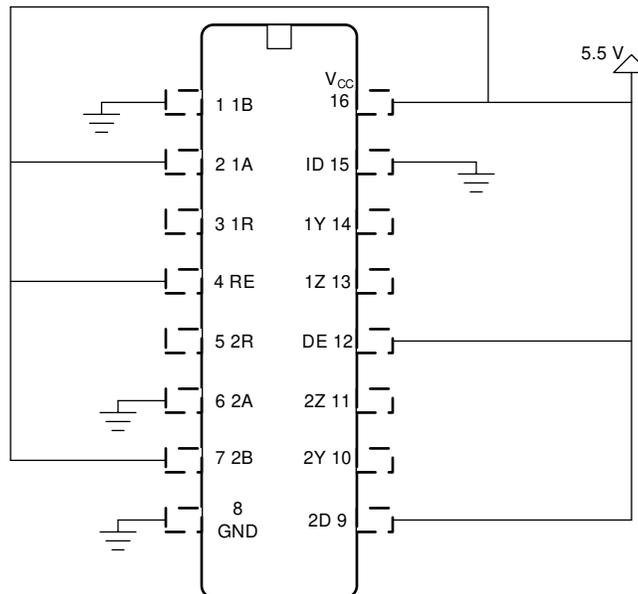


Figure 3-2. SN65C1168E-SEP Bias Diagram

4 Irradiation Facility and Setup

The heavy ion species used for the SEE studies on this product were provided and delivered by the TAMU Cyclotron Radiation Effects Facility [3] using a superconducting cyclotron and advanced electron cyclotron resonance (ECR) ion source. Ion beams are delivered with high uniformity over a 1-in diameter circular cross sectional area for the in-air station. Uniformity is achieved by means of magnetic defocusing. The intensity of the beam is regulated over a broad range spanning several orders of magnitude. For the bulk of these studies, ion fluxes between 10^4 and 10^5 ions/s- cm^2 were used to provide heavy ion fluences between 10^6 and 10^7 ions/ cm^2 . For these experiments Silver (Ag) ions were used. Ion beam uniformity for all tests was in the range of 91% to 98%.

5 Results

5.1 SEL Results

During SEL characterization, the device was heated using forced hot air, maintaining the IC temperature at 125°C. The temperature was monitored by means of a K-type thermocouple attached as close as possible to the IC. The species used for the SEL testing was a silver (⁴⁷Ag) ion with an angle-of-incidence of 0° for an LET_{EFF} = 43 MeV-cm²/mg. The kinetic energy in the vacuum for this ion is 1.634 GeV (15-MeV/amu line). A flux of approximately 10⁵ ions/cm²-s and a fluence of approximately 10⁷ ions were used for two runs. The V_s supply voltage is supplied externally on board at recommended maximum voltage setting of 5.5 V. Run duration to achieve this fluence was approximately 2 minutes. No SEL events were observed during all four runs shown in Table 5-1. Figure 5-1 shows a plot of the current vs time.

Table 5-1. SN65C1168E-SEP SEL Conditions Using⁴⁷Ag at an Angle-of-Incidence of 0°

RUN #	DISTANCE (mm)	TEMPERATURE (°C)	ION	ANGLE	FLUX (ions-cm ² /mg)	FLUENCE (# ions)	LET _{EFF} (MeV.cm ² /mg)
42	40	125	Ag	0°	1.00E+05	2.00E+07	43

No SEL events were observed, indicating that the SN65C1168E-SEP is SEL-immune at LET_{EFF} = 43 MeV-cm²/mg and T = 125°C. Using the MFTF method described in Appendix A and combining (or summing) the fluences of the two runs @ 125°C (2 × 10⁷), the upper-bound cross-section (using a 95% confidence level) is calculated as:

$$\sigma_{SEL} \leq 1.84 \times 10^{-7} \text{ cm}^2 \text{ for LET}_{EFF} = 43 \text{ MeV-cm}^2/\text{mg and } T = 125^\circ\text{C.}$$

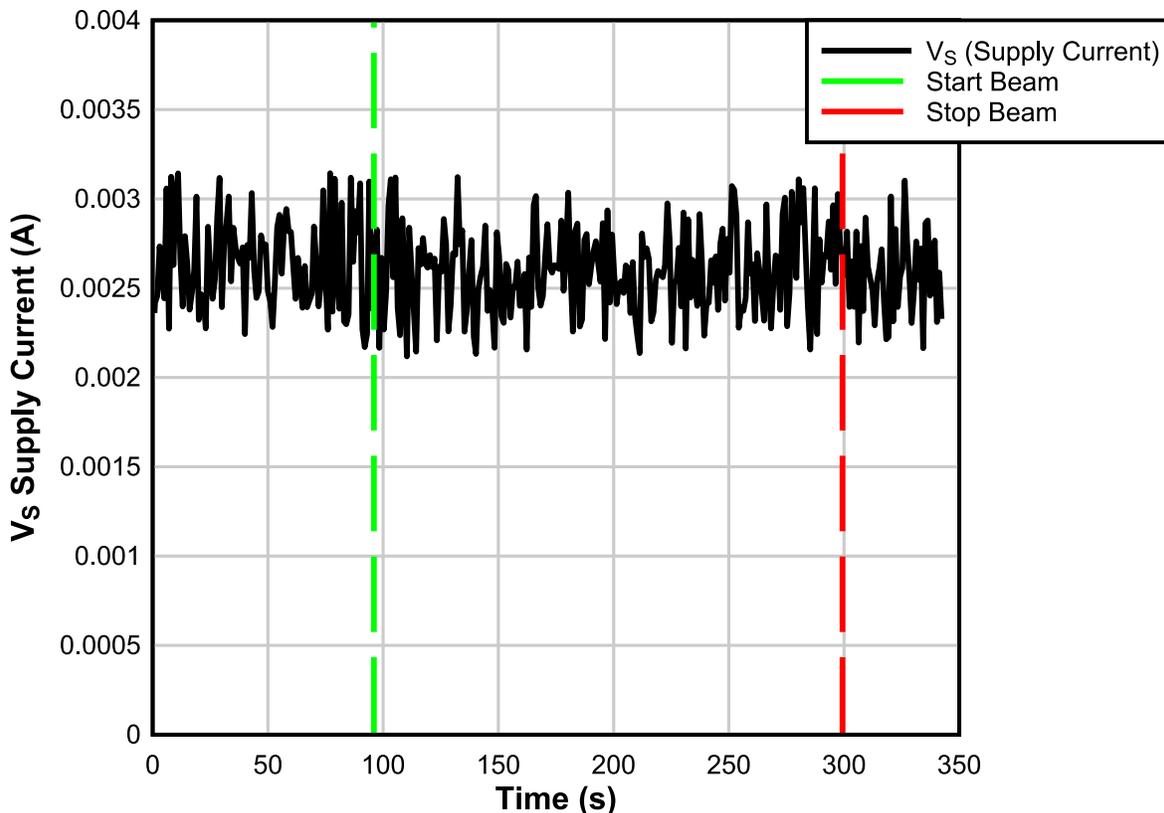


Figure 5-1. Current vs Time (I vs t) Data for V_s Current During SEL

6 Summary

Radiation effects of Radiation Hardened RS-422 Dual Differential Drivers and Receivers in Space Enhanced Plastic, SN65C1168E-SEP, was studied. This device passed total dose rate of up to 30 krad(Si) and is latch-up immune up to $LET_{EFF} = 43 \text{ MeV-cm}^2/\text{mg}$ and $T = 125^\circ\text{C}$.

A Confidence Interval Calculations

For conventional products where hundreds of failures are seen during a single exposure, one can determine the average failure rate of parts being tested in a heavy-ion beam as a function of fluence with high degree of certainty and reasonably tight standard deviation, and thus have a good deal of confidence that the calculated cross-section is accurate.

With radiation hardened parts however, determining the cross-section becomes more difficult since often few, or even, no failures are observed during an entire exposure. Determining the cross-section using an average failure rate with standard deviation is no longer a viable option, and the common practice of assuming a single error occurred at the conclusion of a null-result can end up in a greatly underestimated cross-section.

In cases where observed failures are rare or non-existent, the use of confidence intervals and the chi-squared distribution is indicated. The Chi-Squared distribution is particularly well-suited for the determination of a reliability level when the failures occur at a constant rate. In the case of SEE testing, where the ion events are random in time and position within the irradiation area, one expects a failure rate that is independent of time (presuming that parametric shifts induced by the total ionizing dose do not affect the failure rate), and thus the use of chi-squared statistical techniques is valid (since events are rare an exponential or Poisson distribution is usually used).

In a typical SEE experiment, the device-under-test (DUT) is exposed to a known, fixed fluence (ions/cm²) while the DUT is monitored for failures. This is analogous to fixed-time reliability testing and, more specifically, time-terminated testing, where the reliability test is terminated after a fixed amount of time whether or not a failure has occurred (in the case of SEE tests fluence is substituted for time and hence it is a fixed fluence test [5]). Calculating a confidence interval specifically provides a range of values which is likely to contain the parameter of interest (the actual number of failures/fluence). Confidence intervals are constructed at a specific confidence level. For example, a 95% confidence level implies that if a given number of units were sampled numerous times and a confidence interval estimated for each test, the resulting set of confidence intervals would bracket the true population parameter in about 95% of the cases.

In order to estimate the cross-section from a null-result (no fails observed for a given fluence) with a confidence interval, we start with the standard reliability determination of lower-bound (minimum) mean-time-to-failure for fixed-time testing (an exponential distribution is assumed):

$$MTTF = \frac{2 n T}{\chi^2(d+1); 100(1 - \frac{\alpha}{2})} \quad (1)$$

Where *MTTF* is the minimum (lower-bound) mean-time-to-failure, *n* is the number of units tested (presuming each unit is tested under identical conditions) and *T*, is the test time, and χ^2 is the chi-square distribution evaluated at 100(1 – $\alpha / 2$) confidence level and where *d* is the degrees-of-freedom (the number of failures observed). With slight modification for our purposes we invert the inequality and substitute *F* (fluence) in the place of *T*:

$$MFTF = \frac{2 n F}{\chi^2(d+1); 100(1 - \frac{\alpha}{2})} \quad (2)$$

Where now *MFTF* is mean-fluence-to-failure and *F* is the test fluence, and as before, χ^2 is the chi-square distribution evaluated at 100(1 – $\alpha / 2$) confidence and where *d* is the degrees-of-freedom (the number of failures observed). The inverse relation between *MTTF* and failure rate is mirrored with the *MFTF*. Thus the upper-bound cross-section is obtained by inverting the *MFTF*:

$$\sigma = \frac{\chi^2(d+1); 100(1 - \frac{\alpha}{2})}{2 n F} \quad (3)$$

Assume that all tests are terminated at a total fluence of 10^6 ions/cm². Also assume there are a number of devices with very different performances that are tested under identical conditions. Assume a 95% confidence level ($\sigma = 0.05$). Note that as d increases from 0 events to 100 events the actual confidence interval becomes smaller, indicating that the range of values of the true value of the population parameter (in this case the cross-section) is approaching the mean value + 1 standard deviation. This makes sense when one considers that as more events are observed the statistics are improved such that uncertainty in the actual device performance is reduced.

Table A-1. Experimental Example Calculation of MFTF and σ Using a 95% Confidence Interval

Degrees-of-Freedom (d)	2(d + 1)	$\chi^2 @ 95\%$	Calculated Cross Section (cm ²)		
			Upper-Bound @ 95% Confidence	Mean	Average + Standard Deviation
0	2	7.38	3.69E-06	0.00E+00	0.00E+00
1	4	11.14	5.57E-06	1.00E-06	2.00E-06
2	6	14.45	7.22E-06	2.00E-06	3.41E-06
3	8	17.53	8.77E-06	3.00E-06	4.73E-06
4	10	20.48	1.02E-05	4.00E-06	6.00E-06
5	12	23.34	1.17E-05	5.00E-06	7.24E-06
10	22	36.78	1.84E-05	1.00E-05	1.32E-05
50	102	131.84	6.59E-05	5.00E-05	5.71E-05
100	202	243.25	1.22E-04	1.00E-04	1.10E-04

B References

1. M. Shoga and D. Binder, "Theory of Single Event Latchup in Complementary Metal-Oxide Semiconductor Integrated Circuits", *IEEE Trans. Nucl. Sci.*, Vol. 33(6), Dec. 1986, pp. 1714-1717.
2. G. Bruguier and J. M. Palau, "Single particle-induced latchup", *IEEE Trans. Nucl. Sci.*, Vol. 43(2), Mar. 1996, pp. 522-532.
3. TAMU Radiation Effects Facility website. <http://cyclotron.tamu.edu/ref/>
4. "The Stopping and Range of Ions in Matter" (SRIM) software simulation tools website. www.srim.org/index.htm#SRIMMENU
5. D. Kececioglu, "Reliability and Life Testing Handbook", Vol. 1, PTR Prentice Hall, New Jersey, 1993, pp. 186-193.
6. ISDE CRÈME-MC website. <https://creme.isde.vanderbilt.edu/CREME-MC>
7. A. J. Tylka, J. H. Adams, P. R. Boberg, et al., "CREME96: A Revision of the Cosmic Ray Effects on Micro-Electronics Code", *IEEE Trans. on Nucl. Sci.*, Vol. 44(6), Dec. 1997, pp. 2150-2160.
8. A. J. Tylka, W. F. Dietrich, and P. R. Boberg, "Probability distributions of high-energy solar-heavy-ion fluxes from IMP-8: 1973-1996", *IEEE Trans. on Nucl. Sci.*, Vol. 44(6), Dec. 1997, pp. 2140-2149.

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